IN THE CLAIMS:

Please amend claims 1, 8 and 33 as follows:

Sub D4

1. (Twice Amended): A head assembly comprising:

a mounting surface;

an integrated circuit chip which is mounted on the mounting surface and processes signals; and

a head slider which is provided with a head and is mounted on the mounting surface,

said integrated circuit chip being covered by a layer,

C'd cont'd

a height of the integrated circuit chip, including the layer, being lower than a height of the head slider from the mounting surface.

2. (Original): The head assembly as claimed in claim 1, wherein said layer covering the integrated circuit chip is formed by evaporation.

3. (Original): The head assembly as claimed in claim 2, wherein said layer is made of poly(p-xylylene).

4. (Withdrawn)

5. (Original): The head assembly as claimed in claim 1, wherein said layer covers at lest peripheral portions of the integrated circuit chip.

6. (Withdrawn).

Sub04 Cont

7. (Canceled).

8. (Twice Amended): A disk unit for reading information from and writing information to a disk, comprising:

C1 cont'd

a head assembly having a mounting surface, a head slider provided with a head and mounted on the mounting surface, and an integrated circuit chip which is mounted on the mounting surface and processes information read from and/or written to the disk via the head,

said integrated circuit chip being covered by a layer,

a height of the integrated circuit chip, including the layer, being lower than a height of the head slider from the mounting surface.

9 - 29. (Withdrawn).

30. (Previously Added): The head assembly as claimed in claim 1, wherein said layer covers at least an entire upper surface of the integrated circuit chip.

31-32 (withdrawn)

33. (Amended): A unit for reading information from and writing information to a recording

medium, comprising:

a head assembly having a mounting surface, a head slider provided with a head and mounted on the mounting surface, and an integrated circuit chip which is mounted on the mounting surface and processes information read from and/or written to the recording medium via the head,

said integrated circuit chip being covered by a layer,

a height of the integrated circuit chip, including the layer, being lower than a height of the head slider from the mounting surface.

Please add new claims 34-37 as follows:

34. (New): The head assembly according to claim 1, wherein the mounting surface is substantially flat.

35. (New): The head assembly according to claim 8, wherein the mounting surface is substantially flat.

36. (New): A head assembly comprising:

a mounting surface;

an integrated circuit chip which is mounted so as to be raised above the mounting surface and processes signals; and

a head slider provided with a head,

said integrated circuit chip being covered at least on the corner portions and bumps mounting

the integrated circuit chip raised above the mounting surface by a layer of poly(p-xylylene),

wherein a height of the integrated circuit chip, including the layer, being lower than a height of the head slider from the mounting surface and the layer of poly(p-xylylene) prevents foreign particles from separating from the integrated circuit and interfering with the head assembly.

37. (New): A disk unit for reading information from and writing information to a disk, comprising:

a head assembly having a mounting surface, a head slider provided with a head, and an integrated circuit chip which is mounted so as to be raised above the mounting surface and processes information read from and/or written to the disk via the head,

said integrated circuit chip being covered at least on the corner portions and bumps mounting the integrated circuit chip raised above the mounting surface by a layer of poly(p-xylylene),

wherein a height of the integrated circuit chip, including the layer, being lower than a height of the head slider from the mounting surface and the layer of poly(p-xylylene) prevents foreign particles from separating from the integrated circuit and interfering with the head assembly thereby preventing a crash of the disk unit.